



eUICC SIM Datasheet

V1.1 | JULY 2020

Triple-cut form factor

2FF, 3FF, 4FF

Product Overview

A secure IoT SIM card for a global cell network built for M2M data with easy activation, transparent pricing, and developer-friendly tools.

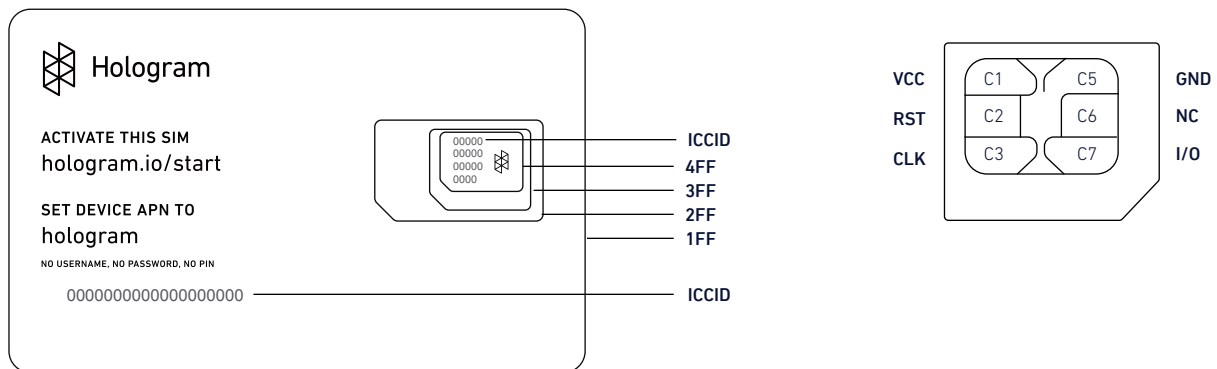
Orderable part numbers

SIM-E-TRI-GL	SIM-E-TRI-LS
SIM-E-TRI-GL-10	SIM-E-TRI-LS-10
SIM-E-TRI-GL-100	SIM-E-TRI-LS-100
SIM-E-TRI-GL-1000	SIM-E-TRI-LS-1000

Network Availability

Works globally with Hologram's 2G through LTE network where coverage is available.
More information: <https://www.hologram.io/pricing/coverage>

Mechanical specifications



Size

1FF	Full-size	85.5 x 53.98 x 0.76 mm
2FF	Mini-SIM	25 x 15 x 0.76 mm
3FF	Micro-SIM	15 x 12 x 0.76 mm
4FF	Mini-SIM	12.3 x 8.8 x 0.76 mm

Pin Definitions

C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware Specifications

Environmental	Standard Grade	Industrial Grade
Temperature	-25–85°C	-40–105°C
Lifespan	25 years @ 25°C	15 years @ 85°C
Lifespan	100K read/write cycles	500K read/write cycles

Electrical	Standard Grade	Industrial Grade
Operating Voltage	1.62V–5.5V	1.62V–5.5V

AC electrical parameters standards

ETSI 3GPP TS 102 221(UICC Terminal Interface Physical & Logical Characteristics)

ETSI TS 102 671 v9.1.0(M2M Physical and Logical Characteristics)

ISO 7816-3 standard for (Cards with Contacts - Electrical interface and transmission protocols)

Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS	 GSMA	SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; SGP.02 v3.2 ; SGP.05 eUICC PP-0089
	 simalliance	eUICC Profile Package v2.1
	 GLOBALPLATFORM®	Product Qualification
Production	 GSMA Security Accreditation Scheme	SAS-UP eUICC : EUM
Remote SIM provisioning	 GSMA	SGP.01 RSP v1.1 ; SGP.11 RSP v3.1 & 3.2; SGP.14 eUICC PKI v1.1 ; SAS-SM

RoHS and REACH Compliance

Hologram, Inc. hereby declares that the aforementioned Hologram products, placed on the European Community market by the Company and its subsidiaries is compliant with Directive 2011/65/EU on the Restriction of Certain Hazardous Substances in Electrical and Electronic Equipment.

More information: <https://www.samsung.com/semiconductor/about-us/global-compliance/>

Embedded form factor

MFF2, QFN8

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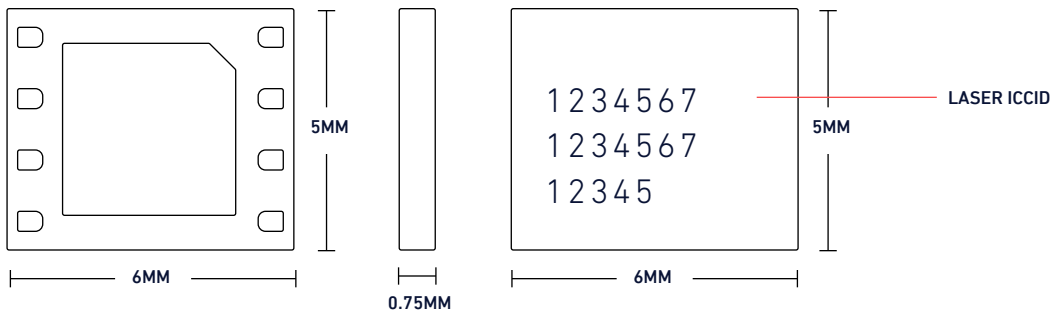
SIM-E-MFF2-GL	SIM-E-MFF2-LS
SIM-E-MFF2-GL-10	SIM-E-MFF2-LS-10
SIM-E-MFF2-GL-100	SIM-E-MFF2-LS-100
SIM-E-MFF2-GL-1000	SIM-E-MFF2-LS-1000

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Mechanical specifications

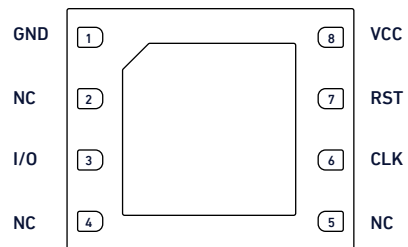
Bottom View



Pin Definitions

1	GND	Ground
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

Top View



Size

6 x 5 x 0.75mm

Hardware Specifications

Environmental	Standard Grade	Industrial Grade
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Lifespan	25 years @ 25°C	15 years @ 85°C
Lifespan	100K read/write cycles	500K read/write cycles

Electrical	Standard Grade	Industrial Grade
Operating Voltage	1.62V–5.5V	1.62V–5.5V







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